

SPECIFICATION 产品规格书

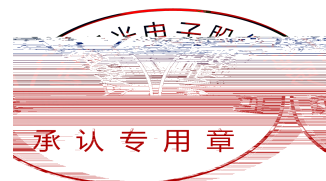


REFOND P/N 产品型号

RF-TVH*PA14EAN-****

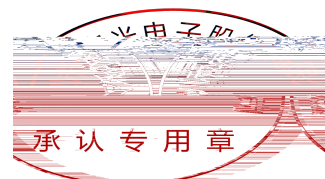
R&D 研发

Mass Product 量产供货



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1. Description 产品介绍

1.1 Description 描述

The White LED which was fabricated using a blue chip and the phosphor, outline size 4.0mm 1.4mm 0.65mm. 此产品为白光LED，是由蓝光芯片激发荧光粉而形成。产品尺寸：4.0mm 1.4mm 0.65mm。

1.1.1 Features 特征

PLCC Package. PLCC封装

Extremely wide viewing angle. 发光角度大

Suitable for all SMT assembly and solder process. 适用于所有的SMT组装和焊接工艺

Available on tape and reel. 适用于载带及卷轴

Moisture sensitivity level: Level 3 334.37 Tm[A]-12(v)10(a)-3(i)-7(la 0 53cm/5 Tm[3 334JET EMC /

1.2 Package Dimension 产品尺寸

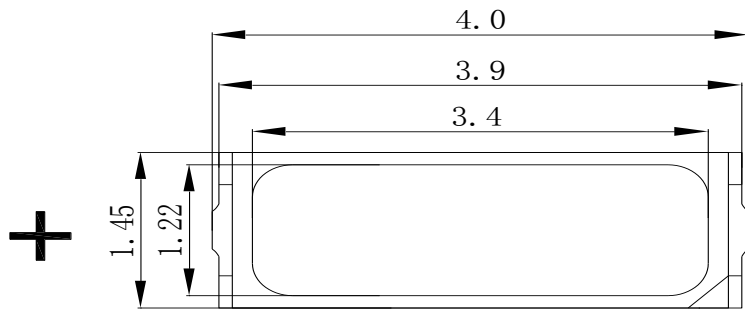


Fig.1-1 Top view 正面视图

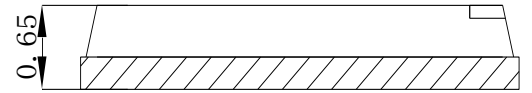


Fig.1-2 Side view 侧面视图

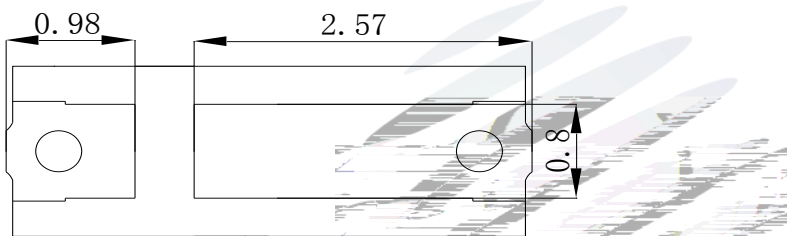


Fig.1-3 Bottom view 背面视图

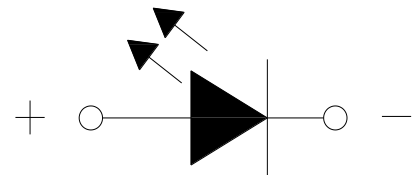


Fig.1-4 Polarity 极性

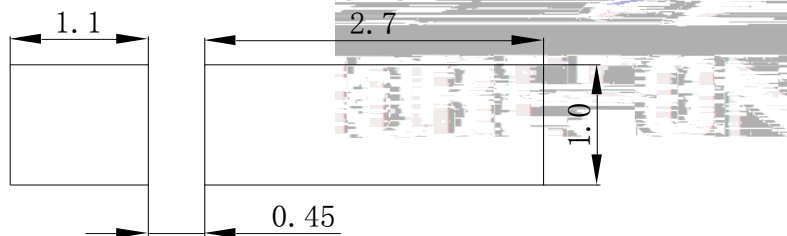


Fig.1-5 Soldering patterns 推荐焊盘

Notes 备注:

(1) All dimensions units are millimeters. 所有尺寸标注单位为毫米

(2) All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted. 除特别标注外, 所有尺寸公差为 ± 0.2 毫米

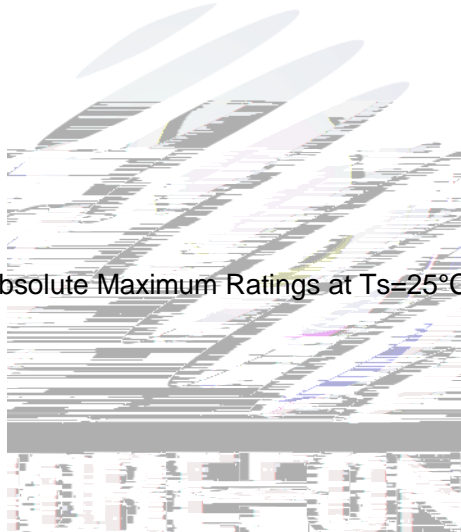


1.3 Product Parameters 产品参数

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

Item 项目	Symbol 符号	Test condition 测试条件	Value			Unit 单位
			Min. (最小值)	Typ (典型值)	Max. (最大值)	
Forward Voltage (正向电压)	V _F	I _F =90mA	2.8	---	3.6	V
Reverse Current (漏电流)	I _R	V _R =5V	---	---	10	uA
Luminous Flux (光通量)	Φ	I _F =90mA	26	---	42	Lm

Table 1-2 Absolute Maximum Ratings at Ts=25°C 绝对最大值



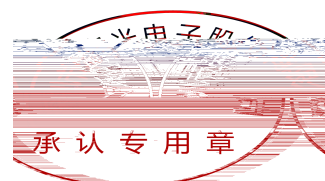
Notes 备注:

- (1) 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms,占空比1/10.
- (2) The above forward voltage measurement allowance tolerance is $\pm 0.1V$. 以上所示电压测量误差 $\pm 0.1V$.
- (3) The above color coordinates measurement allowance tolerance is 0.005. 以上所示坐标测量误差 0.005.
- (4) The above luminous intensity measurement allowance tolerance $\pm 5\%$. 以上所示发光强度的测试允许公差为 $\pm 5\%$.
- (5) Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值。
- (6) All measurements were made under the standardized environment of Refond. 所有测试都是基于瑞丰现有的标准测试平台。
- (7) When the LEDs are in operation the maximum current should be decided after measuring the package temperature junction temperature should not exceed the maximum rate. LED 使用最大电流需要根据散热条件确定, 结温不能超过最大值。
- (8) ESD yield is over 90% at 2000V ESD (HBM). ESD protection during products handing is needed. 90%的LED 通过人体模式ESD2000V 测试, 在操作时请注意静电防护。

1.4 Bin Range Of Forward Voltage and Luminous Flux (IF=90mA)电压与流明分BIN 范围(IF=90mA)

Table 1-3 Bin Range Of Forward Voltage and Luminous Flux电压与流明分BIN范围(IF=90mA)

V _F (V)	G1	G2	H1	H2	I1	I2	J1	J2
		2.8-2.9	2.9-3.0	3.0-3.1	3.1-3.2	3.2-3.3	3.3-3.4	3.4-3.5
Φ (lm)	T26	T28	T30	T32	T34	T36	T38	T40
	26-28	28-30	30-32	32-34	34-36	36-38	38-40	40-42



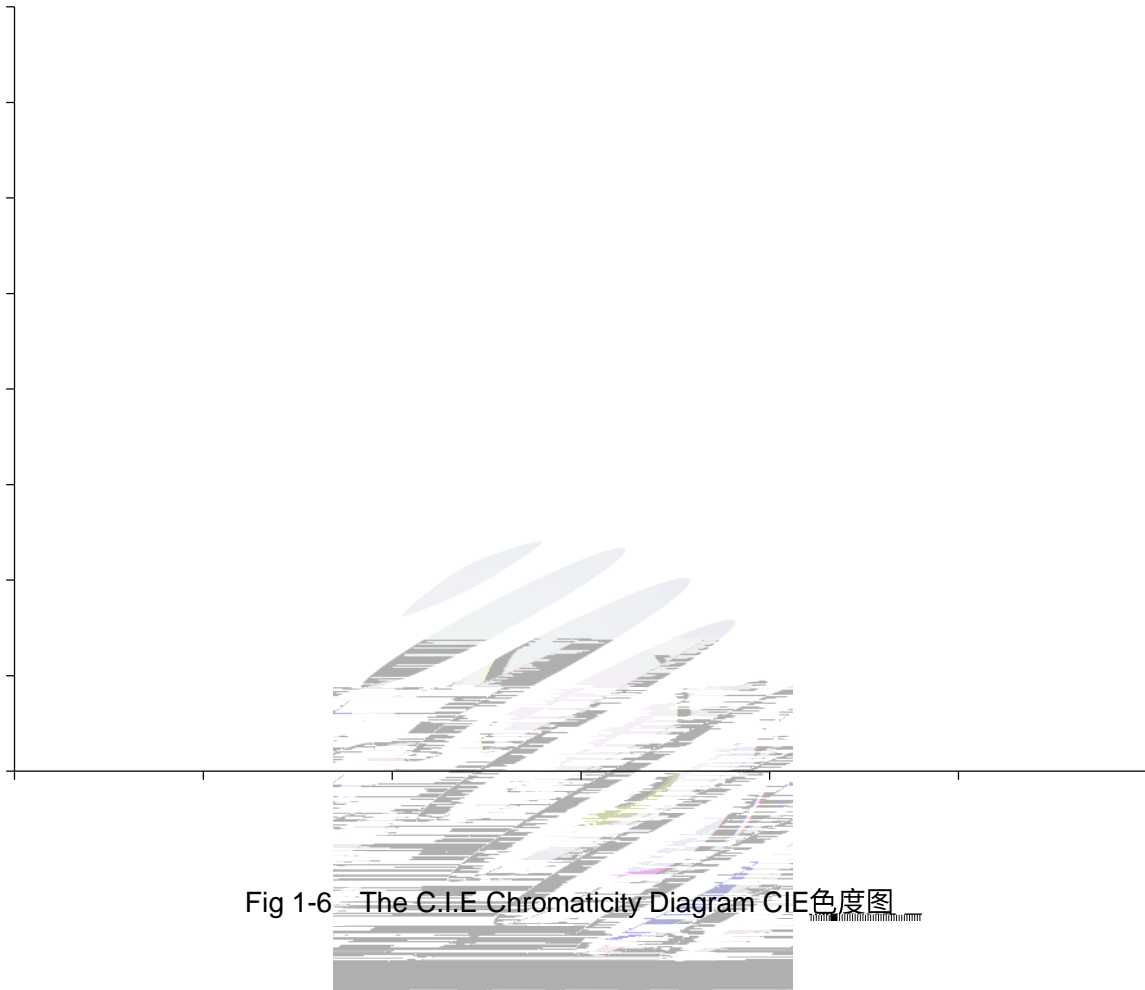
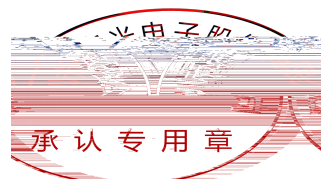


Fig 1-6 The C.I.E Chromaticity Diagram CIE色度图

Table 1-4 The C.I.E Chromaticity Diagram CIE色度图

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
D00	0.3025	0.2723	0.2958	0.2760	0.3003	0.2850	0.3070	0.2813
D01	0.2980	0.2633	0.2913	0.2670	0.2958	0.2760	0.3025	0.2723
D02	0.2935	0.2543	0.2868	0.2580	0.2913	0.2670	0.2980	0.2633
D03	0.2890	0.2453	0.2823	0.2490	0.2868	0.2580	0.2935	0.2543
D04	0.2845	0.2363	0.2778	0.2400	0.2823	0.2490	0.2890	0.2453
D05	0.2800	0.2273	0.2733	0.2310	0.2778	0.2400	0.2845	0.2363
D06	0.2755	0.2183	0.2688	0.2220	0.2733	0.2310	0.2800	0.2273
D07	0.2710	0.2093	0.2643	0.2130	0.2688	0.2220	0.2755	0.2183
D08	0.2665	0.2003	0.2598	0.2040	0.2643	0.2130	0.2710	0.2093
D09	0.2620	0.1913	0.2553	0.1950	0.2598	0.2040	0.2665	0.2003
D10	0.2575	0.1823	0.2508	0.1860	0.2553	0.1950	0.2620	0.1913
D20	0.3070	0.2813	0.3003	0.2850	0.3048	0.2940	0.3115	0.2903
D21	0.3115	0.2903	0.3048	0.2940	0.3093	0.3030	0.3160	0.2993
D22	0.3160	0.2993	0.3093	0.3030	0.3138	0.3120	0.3205	0.3083
H00	0.2958	0.2760	0.2891	0.2797	0.2936	0.2887	0.3003	0.2850

H01	0.2913	0.2670	0.2846	0.2707	0.2891	0.2797	0.2958	0.2760
H02	0.2868	0.2580	0.2801	0.2617	0.2846	0.2707	0.2913	0.2670
H03	0.2823	0.2490	0.2756	0.2527	0.2801	0.2617	0.2868	0.2580
H04	0.2778	0.2400	0.2711	0.2437	0.2756	0.2527	0.2823	0.2490
H05	0.2733	0.2310	0.2666	0.2347	0.2711	0.2437	0.2778	0.2400
H06	0.2688	0.2220	0.2621	0.2257	0.2666	0.2347	0.2733	0.2310
H07	0.2643	0.2130	0.2576	0.2167	0.2621	0.2257	0.2688	0.2220
H08	0.2598	0.2040	0.2531	0.2077	0.2576	0.2167	0.2643	0.2130
H09	0.2553	0.1950	0.2486	0.1987	0.2531	0.2077	0.2598	0.2040
H10	0.2508	0.1860	0.2441	0.1897	0.2486	0.1987	0.2553	0.1950
H20	0.3003	0.2850	0.2936	0.2887	0.2981	0.2977	0.3048	0.2940
H21	0.3048	0.2940	0.2981	0.2977	0.3026	0.3067	0.3093	0.3030
H22	0.3071	0.3157	0.3026	0.3067	0.3093	0.3030	0.3138	0.3120
K00	0.2891	0.2797	0.2824	0.2834	0.2869	0.2924	0.2936	0.2887
K01	0.2846	0.2707	0.2779	0.2744	0.2824	0.2834	0.2891	0.2797
K02	0.2801	0.2617	0.2734	0.2654	0.2779	0.2744	0.2846	0.2707
K03	0.2756	0.2527	0.2689	0.2564	0.2734	0.2654	0.2801	0.2617
K04	0.2711	0.2437	0.2644	0.2474	0.2689	0.2564	0.2756	0.2527
K05	0.2666	0.2347	0.2599	0.2384	0.2644	0.2474	0.2711	0.2437
K06	0.2621	0.2257	0.2554	0.2294	0.2599	0.2384	0.2666	0.2347
K07	0.2576	0.2167	0.2509	0.2204	0.2554	0.2294	0.2621	0.2257
K08	0.2531	0.2077	0.2464	0.2114	0.2509	0.2204	0.2576	0.2167
K09	0.2486	0.1987	0.2419	0.2024	0.2464	0.2114	0.2531	0.2077
K10	0.2441	0.1897	0.2374	0.1934	0.2419	0.2024	0.2486	0.1897
K20	0.2936	0.2887	0.2869	0.2924	0.2914	0.3014	0.2981	0.2977
K21	0.2981	0.2977	0.2914	0.3014	0.2959	0.3104	0.3026	0.3067
K22	0.3004	0.3194	0.2959	0.3104	0.3026	0.3067	0.3071	0.3157
T00	0.2824	0.2834	0.2757	0.2871	0.2802	0.2961	0.2869	0.2924
T01	0.2779	0.2744	0.2712	0.2781	0.2757	0.2871	0.2824	0.2834
T02	0.2734	0.2654	0.2667	0.2691	0.2712	0.2781	0.2779	0.2744
T03	0.2689	0.2564	0.2622	0.2601	0.2667	0.2691	0.2734	0.2654
T04	0.2644	0.2474	0.2577	0.2511	0.2622	0.2601	0.2689	0.2564
T05	0.2599	0.2384	0.2532	0.2421	0.2577	0.2511	0.2644	0.2474
T06	0.2554	0.2294	0.2487	0.2331	0.2532	0.2421	0.2599	0.2384
T07	0.2509	0.2204	0.2442	0.2241	0.2487	0.2331	0.2554	0.2294
T08	0.2464	0.2114	0.2397	0.2151	0.2442	0.2241	0.2509	0.2204
T09	0.2419	0.2024	0.2352	0.2061	0.2397	0.2151	0.2464	0.2114
T10	0.2374	0.1934	0.2307	0.1971	0.2352	0.2061	0.2419	0.2024
T20	0.2869	0.2924	0.2802	0.2961	0.2847	0.3051	0.2914	0.3014
T21	0.2914	0.3014	0.2847	0.3051	0.2892	0.3141	0.2959	0.3104
T22	0.2937	0.3231	0.2892	0.3141	0.2959	0.3104	0.3004	0.3194



1.5 Typical optical characteristics curves 典型光学特性曲线

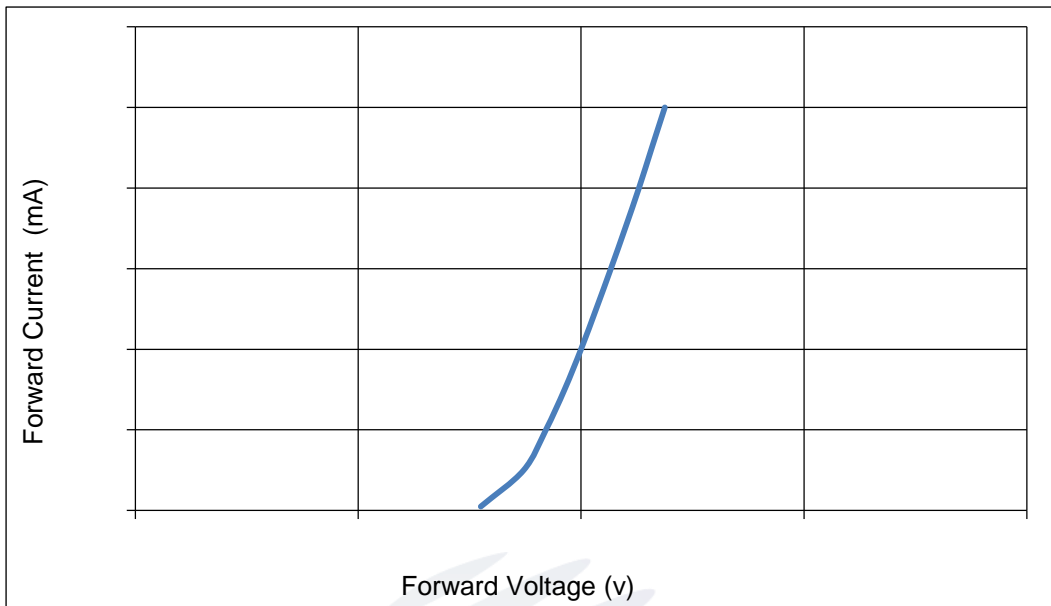


Fig 1-7 Forward Voltage Vs. Forward Current 伏安特性曲线

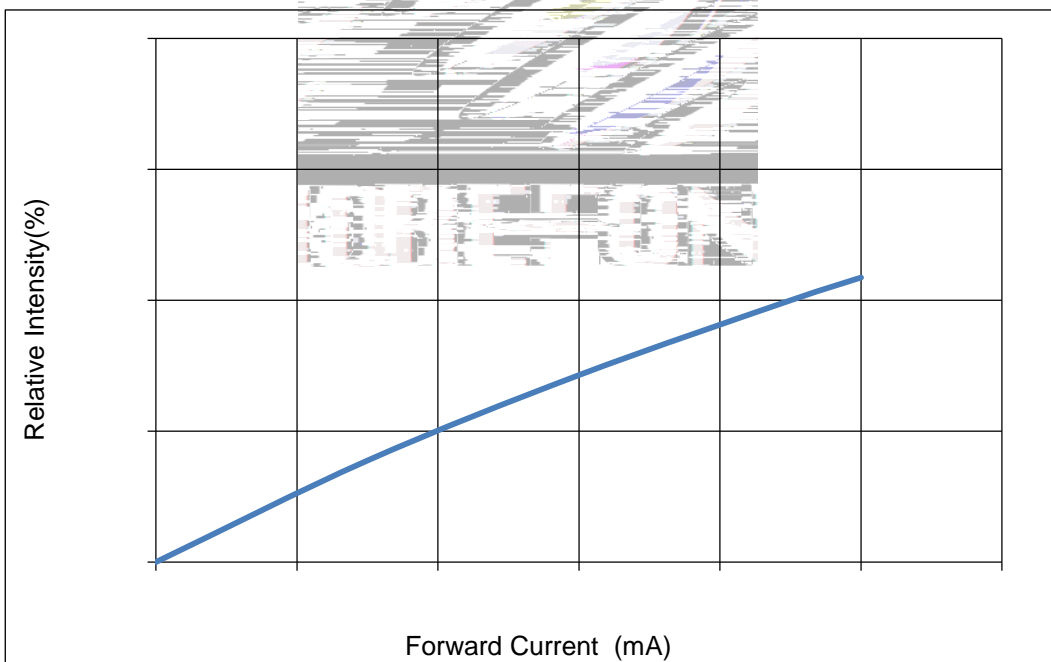


Fig 1-8 Forward Current Vs. Relative Intensity 正向电流与相对光强特性曲线



Fig 1-9 Solder Temperature Vs Relative Intensity 管脚温度与相对光强特性曲线

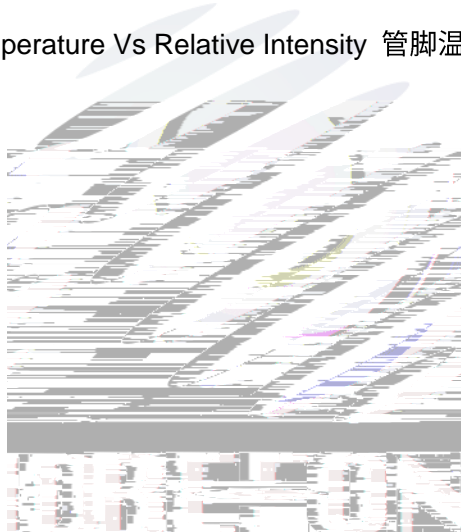


Fig 1-10 Solder Temperature Vs Forward Current 管脚温度与正向电流特性曲线

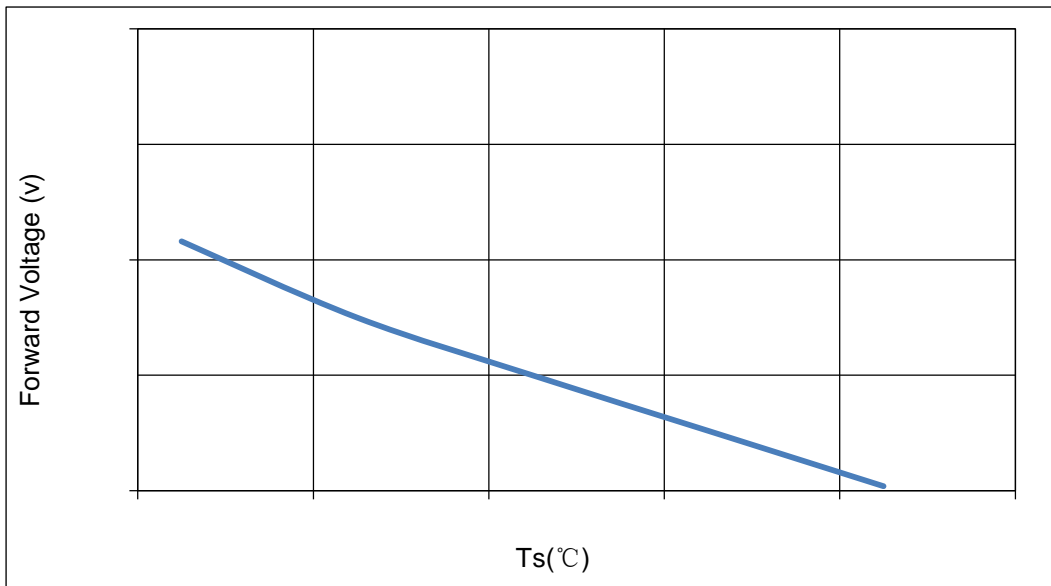


Fig 1-11 Forward Voltage Vs Solder Temperature 电压与管脚温度特性曲线

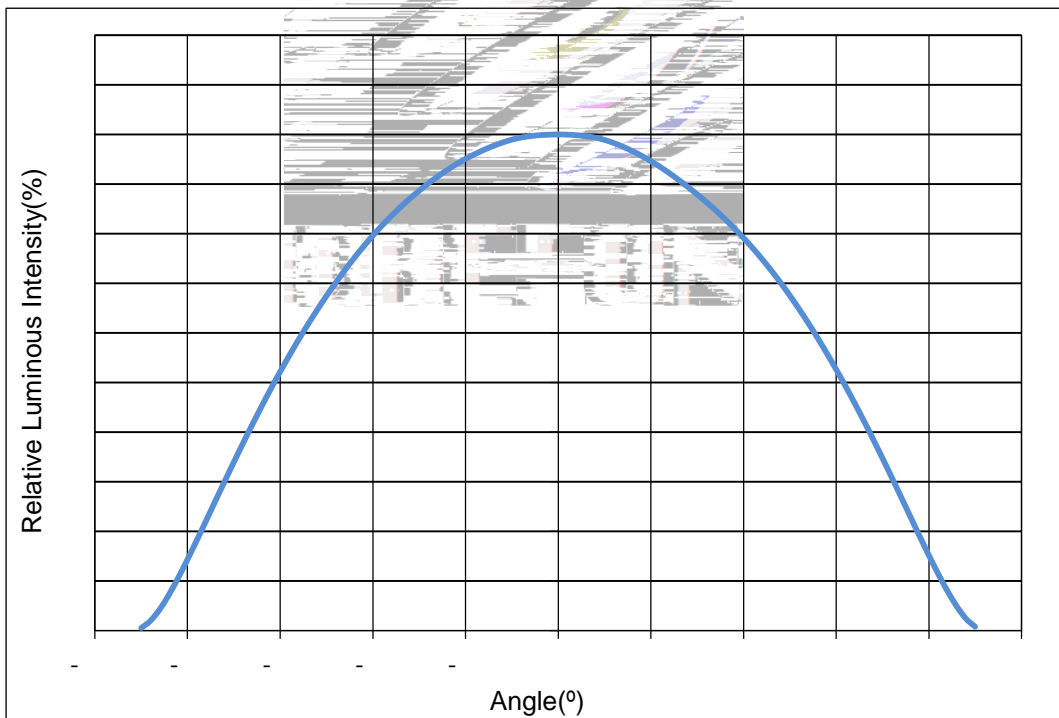


Fig 1-12 Radiation diagram 辐射特性曲线



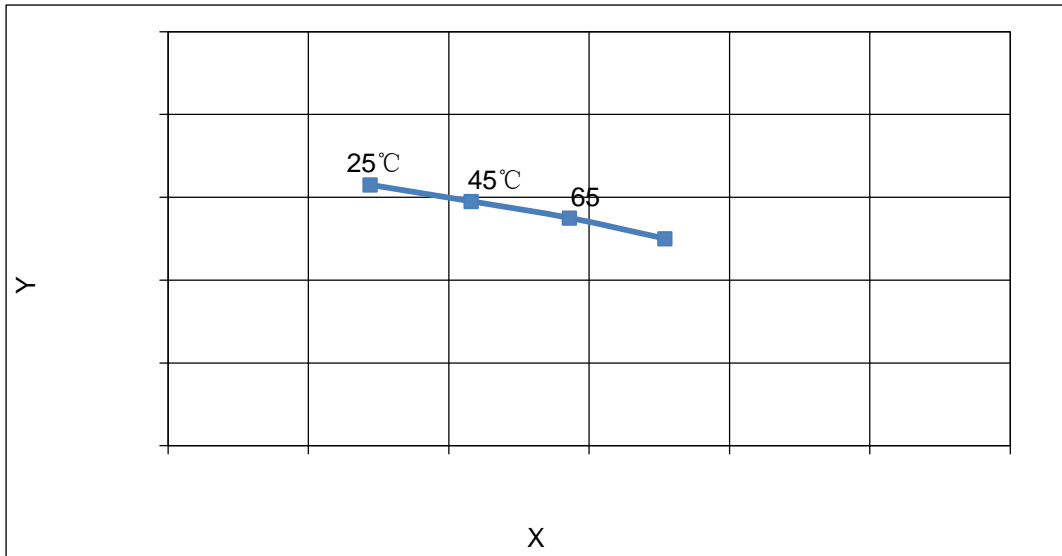
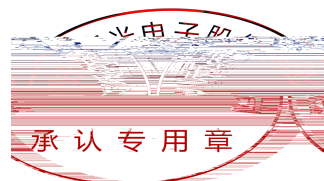
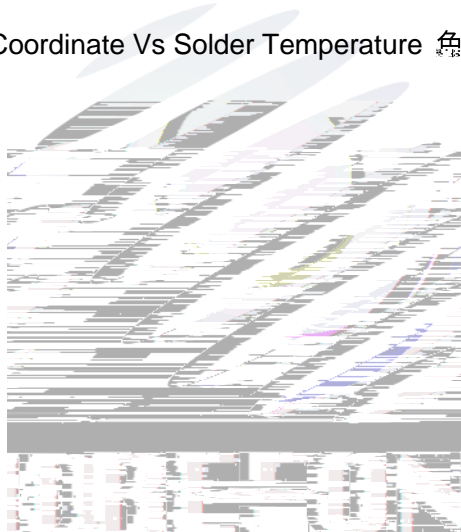


Fig 1-13 Chromaticity Coordinate Vs Solder Temperature 色坐标与管脚温度特性曲线



2.1.3 Label Form Specification 标签规格

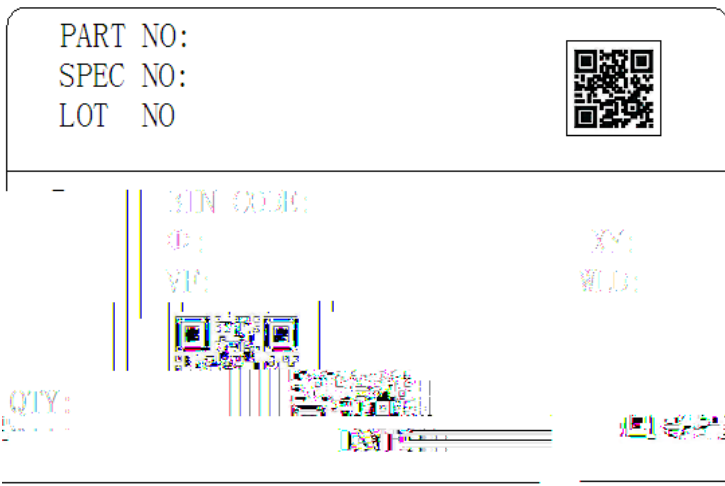


Fig 2-3 Label Form Specification 标签规格

Table 2-2 Label Form Specification 标签规格

PART NO.	Part Number	品名
SPEC NO.	Spec Number	规格
LOT NO.	Lot Number	批次号
BIN CODE	Bin Code	参数代码
Φ	Luminous flux	光通量
XY	Chromaticity Bin	色区
VF	Forward Voltage	正向电压
WLD	Wavelength	波长代码
QTY	Packing Quantity	数量
DATE	Made Date	生产日期

2.1.4 Moisture Resistant Packing Process 防潮包装过程

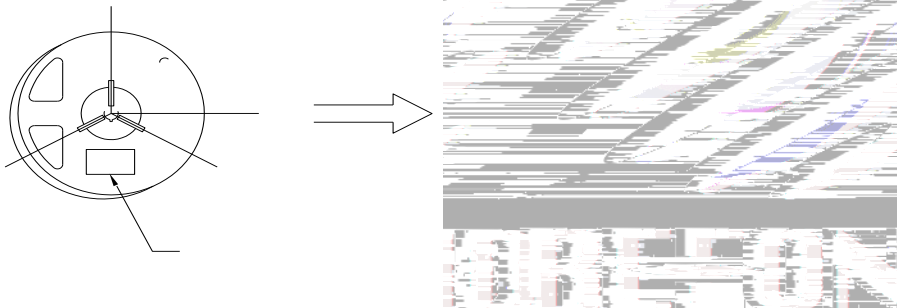


Fig 2-4 Moisture Resistant Packing Process 防潮包装过程

2.1.5 Cardboard Box 纸箱

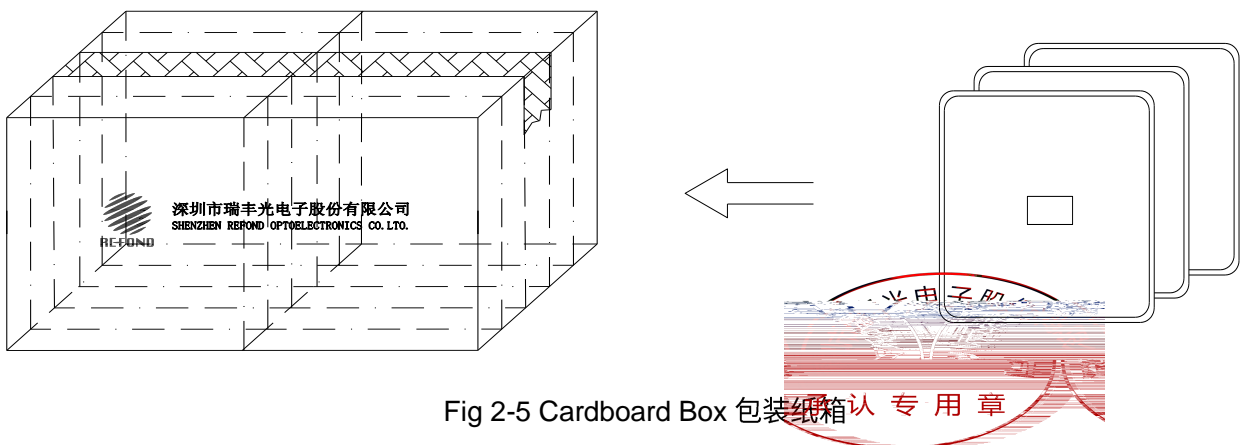


Fig 2-5 Cardboard Box 包装纸箱

2.1.6 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Reliability Test Items And Conditions 信赖性测试项目及条件

Test Items 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260°Cmax T=10 sec	2times	20Pcs	0/1
Thermal Shock 冷热冲击	JEITAED-4701 300 307	-40°C 15min ↑↓10s 100°C 15min	100 cycle	20Pcs	0/1
High Temperature Storage 高温保存	JEITAED-4701 200 201	Temp:100°C	1000Hrs	20Pcs	0/1
Low Temperature Storage 低温保存	JEITA ED-4701 200 202	Temp:-40°C	1000Hrs	20Pcs	0/1
Life Test 常温通电	JESD22-A108	T _A =25°C I _F =100mA	1000Hrs	10Pcs	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60°C/ 90%RH I _F =100mA	500Hrs	10Pcs	0/1
Temperature Humidity Storage 高温高湿储存	JEITA ED-4701 100 103	T _A =85°C RH=85%	500Hrs	20Pcs	0/1



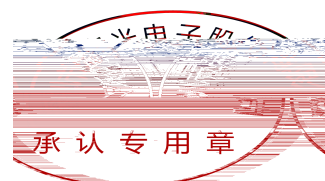
2.1.7 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria For Judging Damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	V_F	$I_F=100mA$	-	U.S.L*)x1.1
Reverse Current 反向电流	I_R	$V_R = 5V$	-	U.S.L*)x2.0
Luminous Flux 光通量	Φ	$I_F=100mA$	L.S.L*)x0.7	-

NOTES 备注:

- (1) U.S.L: Upper standard level 规格上限 ; L.S.L: Lower standard level 规格下限
- (2) The Reliability tests are based on Refond existing test platform. 信赖性测试基于瑞丰现有的测试平台。
- (3) The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。



3. SMT Reflow Soldering Instructions SMT回流焊说明

Fig 3-1 3. SMT Reflow Soldering Instructions SMT 回流焊说明

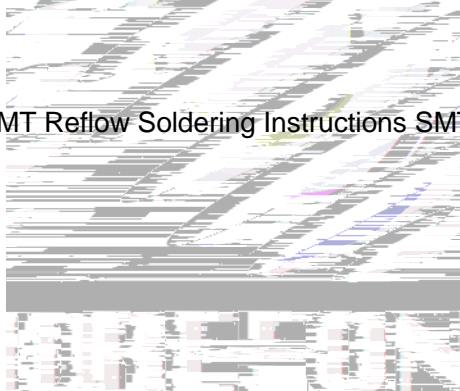
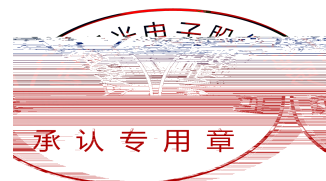


Table 3-1 SMT Reflow Soldering Instructions SMT 回流焊说明





4. Handling Precautions 使用注意事

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM. 这只是一个建议，不作任何品质担保。

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. 为了防止外界物质进入 LED 内部以造成 LED 的损伤，所处环境及所用套件等等，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议，不作任何品质担保。

(3)





Table 4-1 Storage 儲存

Conditions 种类		Temperature 温度	Humidity 湿度	Time 时间
Storage 儲存	Before Opening Aluminum Bag 拆包前	$\leq 30^{\circ}\text{C}$	$\leq 75\%$	Within 1 Year From Date 一年内
	After Opening Aluminum Bag 拆包后	$\leq 30^{\circ}\text{C}$	$\leq 60\%$	24hours 24小时
Baking 烘烤		$60 \pm 5^{\circ}\text{C}$	-	$\geq 24\text{hours}$ 大于24小时

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time baking treatment should be performed after unpacking and based on the following condition 65 5 for above 24 hours. 如果干燥剂失效或产品不符合以上有效储存条件，需拆包后进行烘烤，烘烤条件：60 ±5°C，大于 24 小时。

If the package is flatulence or damaged, please notify the sales staff to assist. 如果包装胀气或者破损，请通知销售人员协助处理。

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 像其他的半导体电子器件一样，LED 对静电过流击穿非常敏感，需要做好防护。

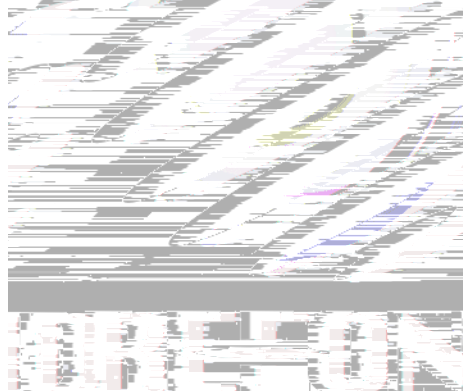
(10) Other points for attention, please refer to our relevant information.

其它注意事项请参照瑞丰相关资料。





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Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，若有冲突以中文版本为准。

